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### IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the application of: Y. INOUE et al.

Serial No.: 08/921,250

Filed: August 29, 1997

OIPE OCT 17 2000 W

PATENT APPLICA

Art Uni

Examiner: G. Got

For: FABRICATION METHOD OF SEMICONDUCTOR DEVICE AND ABRASIVE LIQUID

**USED THEREIN** 

### AMENDMENT TRANSMITTAL

Director of Patents and Trademarks Washington, D.C. 20231

October 17, 2000

Sir:

- Transmitted herewith is an Amendment in the above-identified application.
- Small Entity status of this application under 37 CFR 1.9 and 1.27 has been established by a verific statement previously submitted.
- \_\_ A verified statement to establish Small Entity status under 37 CFR 1.9 and 1.27 is enclosed.

The fee has been calculated as shown below:

	CLAIMS AS AMENDED						
	Claims Remaining After Amendment	Highest Number Previously Paid For		Present Extra	Small Entity	Large Entity	Additional
Total Claims	26	30	=	0	X \$9	X \$18	0
Independent Claims	8	8	=	o ·	X\$40	X \$80	0 .
## First Presentation of Multiple Dependent Claims \$135 270						0.00	
TOTAL FEES ENCLOSED:							-0-

The Commissioner is hereby authorized to charge payment for any additional fees associated with this communication or credit any overpayment to Deposit Account No. <u>01-2340</u>. Two duplicates of this sheet are attached.

Respectfully submitted,

ARMSTRONG, WESTERMAN, HATTORI, McLELAND & NAUGHTON

Stephen G. Adrian Attorney for Applicants Reg. No. 32,878

Atty. Docket No. 970813 1725 K Street, N.W., Suite 1000 Washington, DC 20006 Tel: (202) 659-2930 SGA/arf

# IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the application of: Y. INOUE et al

PATENT APPLICATION

Serial No.: 08/921,250

Art Unit: 1763

Filed: August 29, 1997

Examiner: G. Goudreau

For:

FABRICATION METHOD OF SEMICONDUCTOR DEVICE AND

ABRASIVE LIQUID USED THEREIN

### <u>AMENDMENT</u>

RECEIVED

OCT 2 5 2000

Director of Patents and Trademarks Washington, D.C. 20231

0660U601700

Sir:

In response to the Office Action dated July 18, 2000, please amend the above-identified application as follows:

## IN THE CLAIMS:

Please amend claims 3, 4, 7-11, 13, 17, 18 and 26 as follows:

Claim 3,

line 1, change "8" to --32--; and

line 2, change "planrization" to --planarization--.

Claim 4,

line 1, change "8" to --32--.

7. (Twice Amended) [A] <u>The</u> fabrication method of a semiconductor device <u>according to claim 8. further comprising the step of: [comprising the steps of:</u>

forming a first insulation film on a substrate,

forming a second insulation film on said first insulation film,

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